

WHAT IS CLAIMED IS:

1. A slurry for chemical mechanical polishing,
which comprises a silica polishing material, an oxidizing
agent, a benzotriazole-based compound, a diketone and
5 water.

2. A slurry for chemical mechanical polishing
according to Claim 1, wherein said diketone is at least
one type of a compound selected from the group consisting
10 of 1, 2-diketones, 1, 3-diketones and 1, 4-diketones.

3. A slurry for chemical mechanical polishing
according to Claim 1, wherein a content ratio of said
diketone to said benzotriazole-based compound (diketone /
15 benzotriazole-based compound) is not less than 0.05 but
not greater than 50.

4. A slurry for chemical mechanical polishing
according to Claim 1, wherein a value of a pH is in a
20 range of 1 to 7.

5. A slurry for chemical mechanical polishing
according to Claim 1, wherein said silica polishing
material is colloidal silica.

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